ELLIPTICAL FIN HEAT SINK

907 Series

wakefield-vette

Wakefield-Vette's 900 Series Heat Sinks for Chipset can match up to devices from
Intel, Broadcom, Xilinx, TI, Motorola, ATI, AMD, Nvidia, Vishay, Powerex, Infineon, Microsemi, and many more.

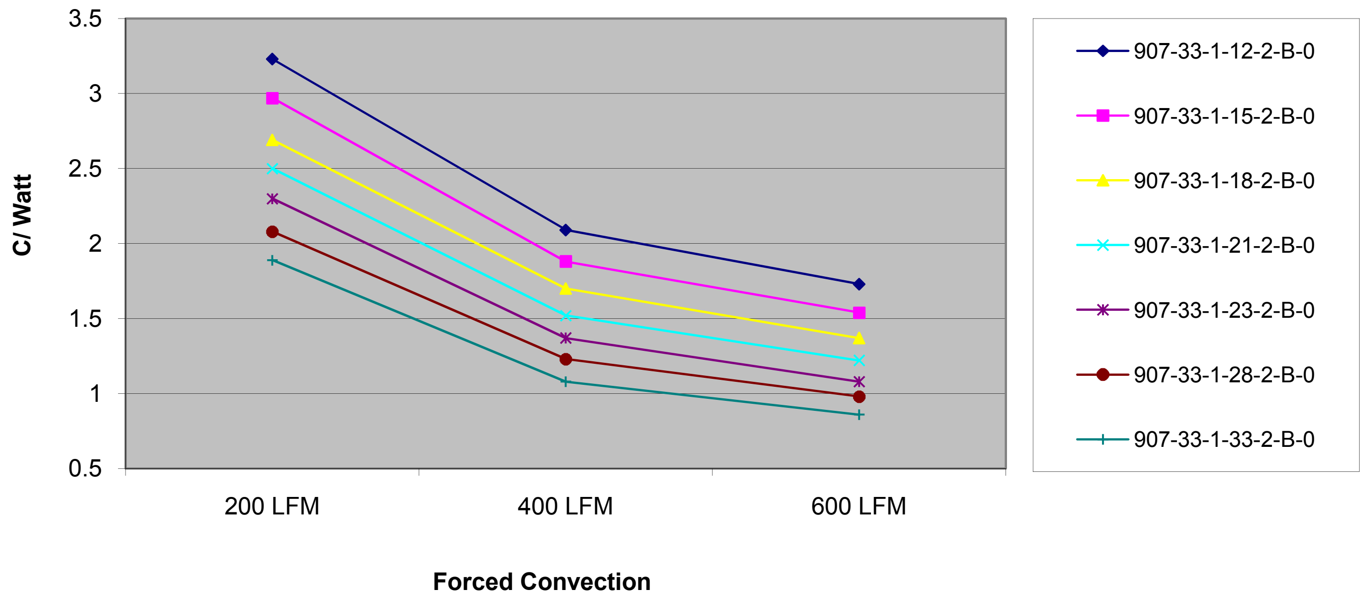
These heat sinks are designed for air flow applications in the Telecom, Data Center, Networking, Cloud Computing, and many more Industries.

Material: AL 6063

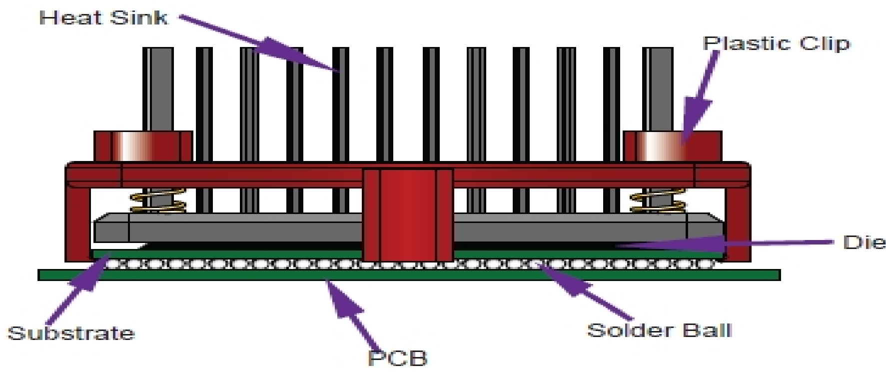
Finish: Black Anodize

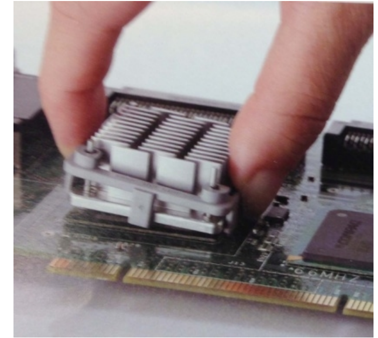
PART #	HEIGHT (mm)	CHIP SIZE (mm)	NATURAL CONVECTION	FORCED CONVECTION (C/W)		
				200 LFM	400 LFM	600 LFM
907-33-1-12-2-B-0	12	33	11.56 C/W	3.23 C/W	2.09 C/W	1.73 C/W
907-33-1-15-2-B-0	15	33	11 C/W	2.97 C/W	1.88 C/W	1.54 C/W
907-33-1-18-2-B-0	18	33	10.45 C/W	2.69 C/W	1.7 C/W	1.37 C/W
907-33-1-21-2-B-0	21	33	9.9 C/W	2.5 C/W	1.52 C/W	1.22 C/W
907-33-1-23-2-B-0	23	33	9.54 C/W	2.3 C/W	1.37 C/W	1.08 C/W
907-33-1-28-2-B-0	28	33	8.62 C/W	2.08 C/W	1.23 C/W	.98 C/W
907-33-1-33-2-B-0	33	33	7.71 C/W	1.89 C/W	1.08 C/W	.86 C/W

THERMAL PERFORMANCE:



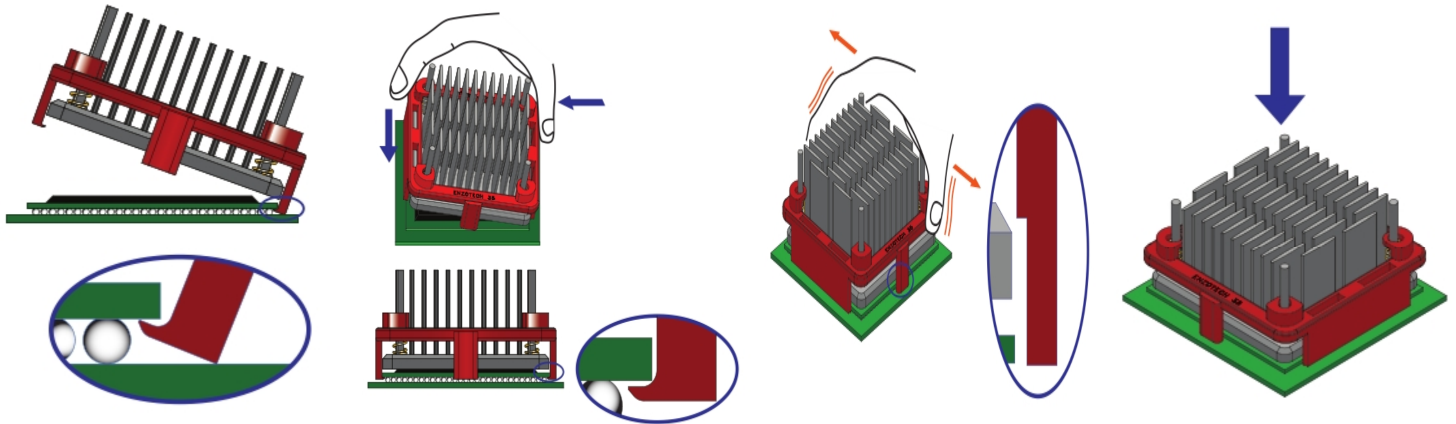
wakefield-vette





Wakefield-Vette's heat sink assembles onto chip set using the space that is between the PCB and the substrate of the solder balls. The solder balls provide a minimal gap of .5mm to .7mm. Attachment feature is below a .4mm thickness. The clipping system will not interfere or damage chip. Contact area is the edge of chip.

ASSEMBLY INSTRUCTION:



Step 1: Hook the clip under one side of the BGA chip set.

Step 2: Rotate assembly down until opposite side clip engages substrate edge of BGA chip set.

Step 3: Make sure the sop rods are clearing from edges of BGA chip set.

Step 4: Press firmly down to make sure clips fully engage edges of chip set. Heat Sink should not move around easily.

Random Vibration Test

Frequency : 5 Hz to 500 Hz
Acceleration : 3.13 grms
P.S.D : 0.01 g2/HZ (5 Hz)
0.02 g2/HZ (20 Hz to 500 Hz)
Test Axis : X, Y, Z axis
Test Time : 10 mins (Each axis)
Total Test Time : 30 mins

SHOCK TEST SPECIFICATION :

Wave Form : Half sine wave
Acceleration : 50 g
Duration Time : 11 ms
No. of Shock : Each axis 3 times
Shock Direction : ±X, ±Y, ±Z axis
Reliability & Communication Testing Instruments